

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions of claims in the application.

1. (currently amended) An apparatus for modifying the surface of a semiconductor wafer, said apparatus comprising
 - a) a textured, three-dimensional, fixed abrasive element comprising a plurality of abrasive particles;
 - b) a resilient element; and
 - c) a rigid element, said rigid element comprising a plurality of rigid segments disposed between said fixed abrasive element and said resilient element, and a plurality of grooves, wherein each of the rigid segments is proximate and spaced apart from at least another of the rigid segments by at least one of the grooves.
2. (canceled)
3. (canceled)
4. (original) The apparatus of claim 1, wherein said fixed abrasive element is bonded to said rigid segments.
5. (original) The apparatus of claim 1, wherein said rigid segments are bonded to said resilient element.
6. (original) The apparatus of claim 1, wherein said fixed abrasive element is capable of moving relative to said rigid segments.

7. (original) The apparatus of claim 1, wherein said fixed abrasive element and said rigid segments are capable of moving relative to said resilient element.

8. (original) The apparatus of claim 1, further comprising

- a. a first web comprising said fixed abrasive element;
- b. a second web comprising said plurality of rigid segments; and
- c. a third web comprising said resilient element.

9. (original) The apparatus of claim 8, wherein said first web and said second web are movable relative to each other.

10. (original) The apparatus of claim 8, wherein said second web and said third web are movable relative to each other.

11. (original) The apparatus of claim 8, wherein said first web and said third web are movable relative to each other.

12. (original) The apparatus of claim 8, wherein said first web, said second web and said third web are movable relative to each other.

13. (previously presented) The apparatus of claim 1, further comprising a web comprising said plurality of rigid segments, said plurality of rigid segments comprising:

a first region comprising a first plurality of rigid segments having a first cross-sectional area; and

a second region comprising a second plurality of rigid segments having a second cross-sectional area,

said first cross-sectional area being different from said second cross-sectional area.

14. (previously presented) The apparatus of claim 1, wherein said plurality of rigid segments comprise a material selected from the group consisting of metal and plastic.

15. (previously presented) A method of modifying the surface of a semiconductor wafer, said method comprising:

- a) contacting the apparatus of claim 1 with a semiconductor wafer; and
- b) moving said semiconductor wafer and said apparatus relative to each other.

16. (previously presented) A method of modifying the surface of a semiconductor wafer comprising:

- a) contacting the fixed abrasive element of the apparatus of claim 13 at a position proximate the first region with a semiconductor wafer;
- b) moving said semiconductor wafer and said apparatus relative to each other;
- c) contacting the fixed abrasive element of the apparatus of claim 13 at a position proximate the second region with the semiconductor wafer; and
- d) moving said semiconductor wafer and said apparatus of claim 13 relative to each other.

17. (previously presented) The method of claim 16, wherein said method further comprises indexing said web from a first position to a second position.